

**Pb-free  
HEAT**



# MU02 Series

Single Color / Light Bar Module

## Features

Light emitting surface (Outer size)	14 x 14 mm (15 x 15 mm) (L x W)
Product features	<ul style="list-style-type: none"> <li>• Single Color (Green, Yellow Green, Orange or Red)</li> <li>• Lead-free soldering compatible</li> <li>• RoHS compliant</li> </ul>
Peak wavelength	Green : 555 nm (5201,5205) : 560 nm (5202) Yellow Green : 570 nm (4201,4205) Orange : 605 nm (3201,3205) Red : 660 nm (2201,2205)
Die materials	Green, Yellow Green : GaP Orange : GaAsP Red : GaAlAs
Soldering methods	TTW (Through The Wave) soldering and manual soldering
Soldering methods	More than 2kV(HBM)
Packing	Tray

## Recommended Applications

Electric Household Appliances, OA/FA, Other General Applications

## Color and Luminous Intensity

Part No.	Material	Emitted Color	Resin Color	Intensity <sup>※1</sup> I <sub>v</sub> (mcd)			Number of Chips
				MIN.	TYP.	I <sub>F</sub>	
MU02-5201	GaP	Green	Green	10	20	20	4
MU02-5205	GaP		Milky White	10	20	20	4
MU02-5202	GaP		Green	15	32	20	4
MU02-4201	GaP	Yellow Green	Yellow	20	42	20	4
MU02-4205	GaP		Milky White	20	42	20	4
MU02-3201	GaAsP	Orange	Orange	10	20	20	4
MU02-3205	GaAsP		Milky White	10	20	20	4
MU02-2201	GaAlAs	Red	Red	20	42	20	4
MU02-2205	GaAlAs		Milky White	20	42	20	4

※1 Luminous Intensity : 4 chips

## Absolute Maximum Ratings

(Ta=25°C)

Item	Symbol	Absolute Maximum Ratings										Unit
		5201	5205	5202	4201	4205	3201	3205	2201	2205		
Power Dissipation <sup>※2</sup>	P <sub>d</sub>	250	250	300	300	300	250	250	240	240	mW	
Forward Current	I <sub>F</sub>	25	25	30	30	30	25	25	30	30	mA	
Pulse Forward Current <sup>※3</sup>	I <sub>FRM</sub>	60	60	60	60	60	60	60	60	60	mA	
Derating (Ta=25°C or higher)	ΔI <sub>F</sub>	0.33	0.33	0.40	0.40	0.40	0.33	0.33	0.40	0.40	mA/°C	
	ΔI <sub>FRM</sub>	0.80	0.80	0.80	0.80	0.80	0.80	0.80	0.80	0.80	mA/°C	
Reverse Voltage	V <sub>R</sub>	4	4	4	4	4	4	4	4	4	V	
Operating Temperature	T <sub>opr</sub>	-40~+85										°C
Storage Temperature	T <sub>stg</sub>	-40~+85										°C

※2 Power Dissipation : 4 chips, The other Items : 1 chip

※3 I<sub>FRM</sub> Measurement condition : Pulse Width ≤ 2ms, Duty ≤ 1/5

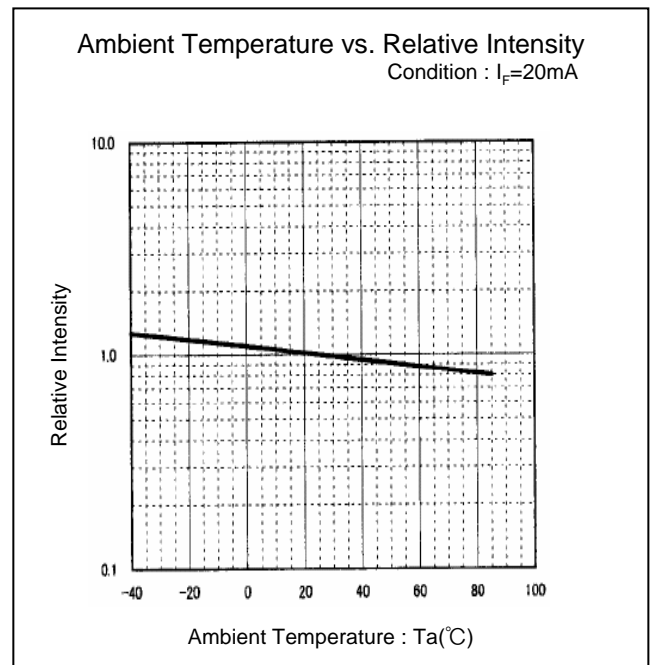
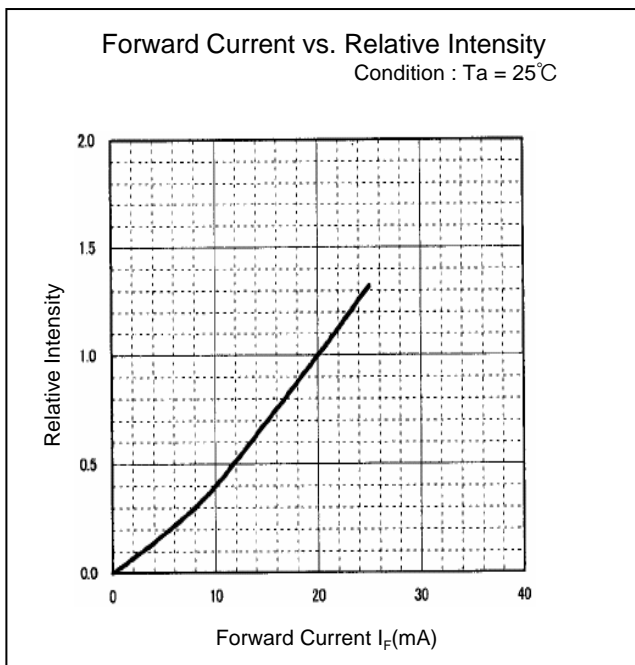
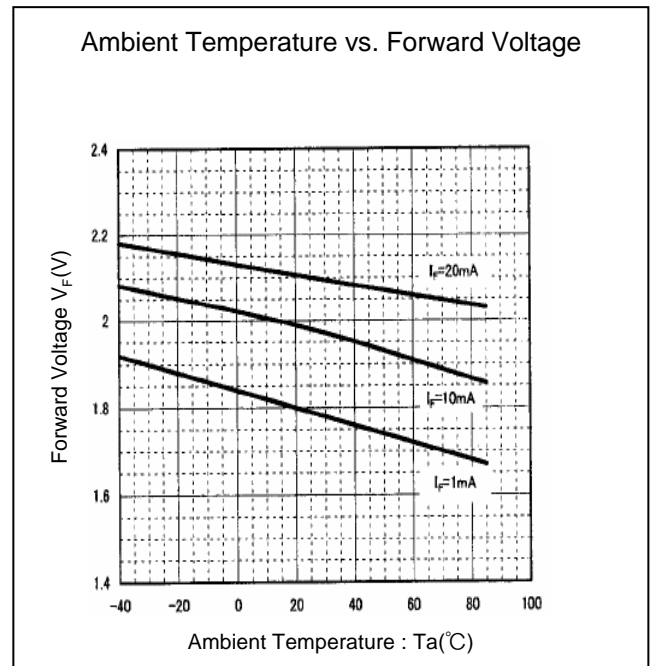
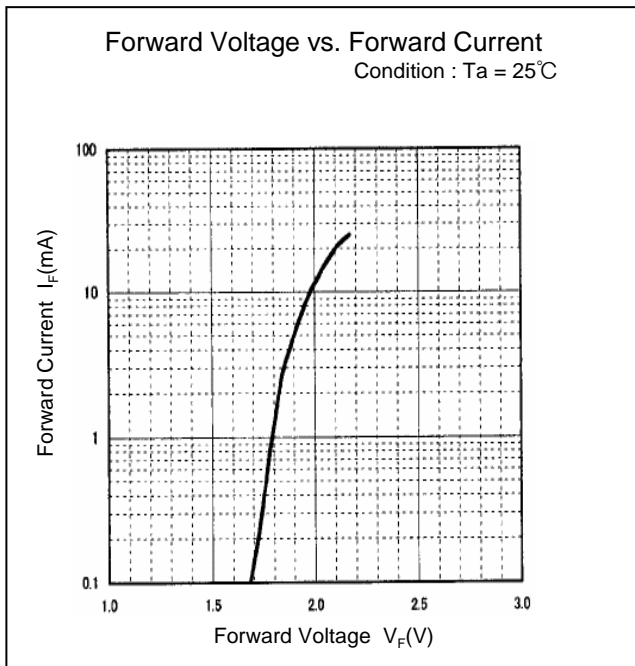
## Electro-Optical Characteristics

(Ta=25°C)

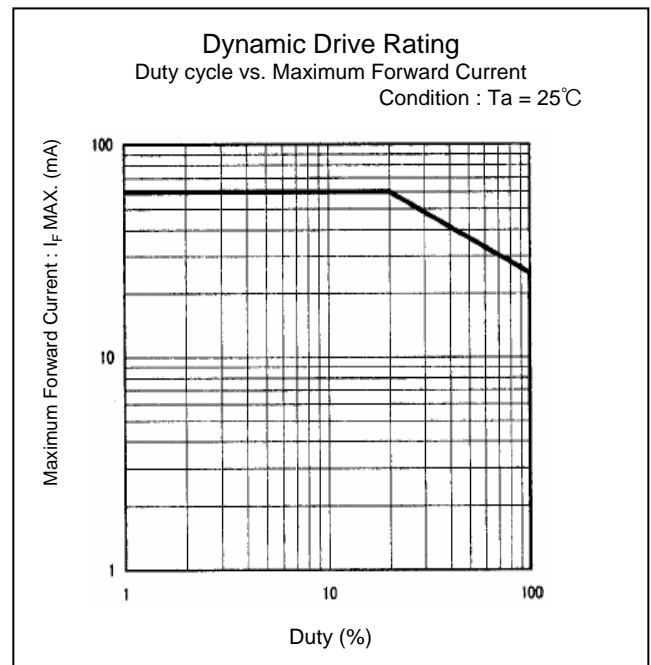
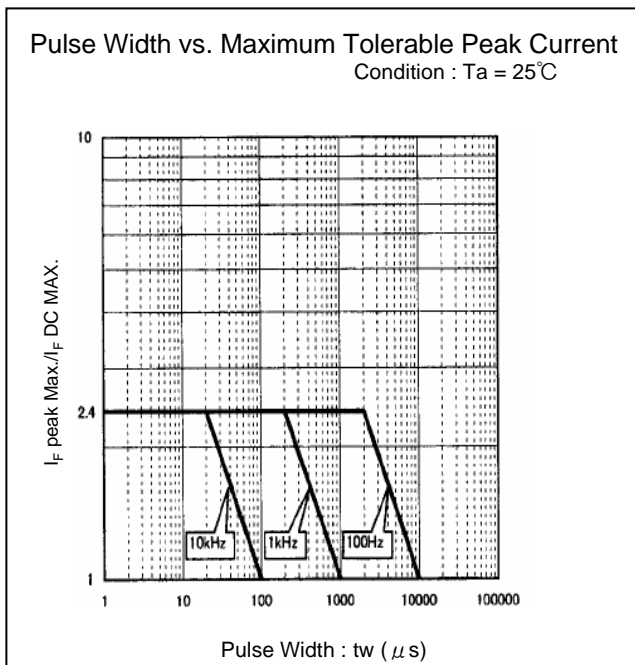
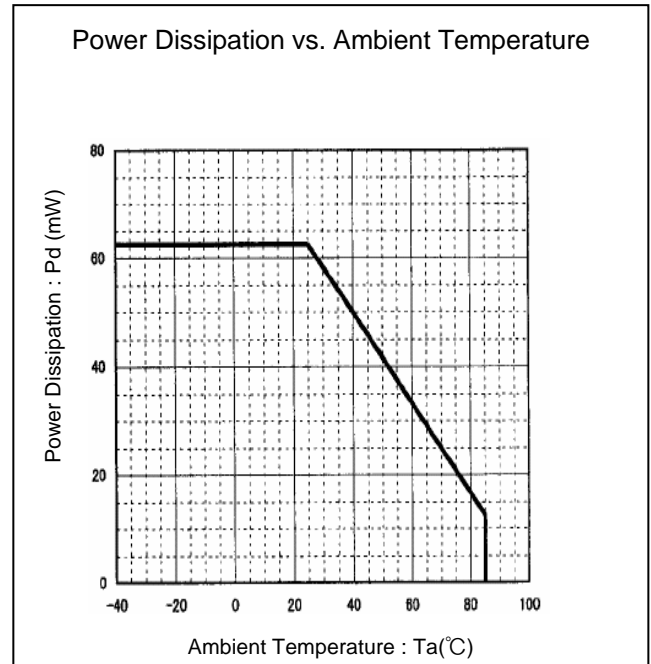
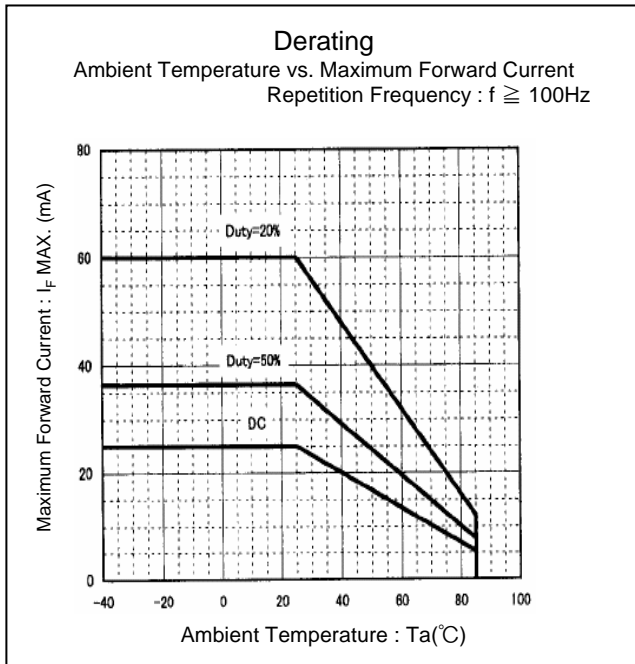
Item	Conditions	Symbol	Characteristics											Unit
				5201	5205	5202	4201	4205	3201	3205	2201	2205		
Forward Voltage	I <sub>F</sub> =20mA	V <sub>F</sub>	TYP.	2.2	2.2	2.1	2.1	2.1	2.2	2.2	1.7	1.7	V	
			MAX.	2.5	2.5	2.5	2.5	2.5	2.5	2.5	2.5	2.0		2.0
Reverse Current	V <sub>R</sub> =4V	I <sub>R</sub>	MAX.	100	100	100	100	100	100	100	100	100	μA	
Peak Wavelength	I <sub>F</sub> =20mA	λ <sub>p</sub>	TYP.	555	555	560	570	570	605	605	660	660	nm	
Spectral Line Half Width	I <sub>F</sub> =20mA	Δλ	TYP.	30	30	30	30	30	30	30	30	30	nm	

※ The above Items : 1 chip

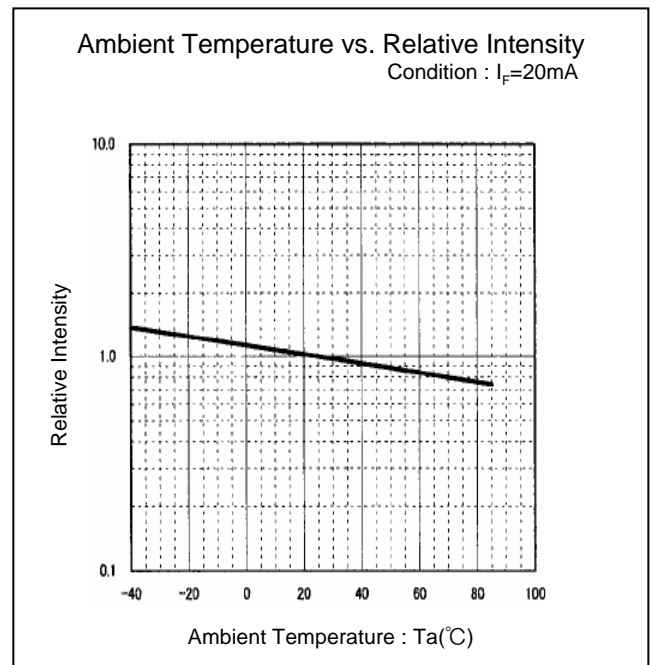
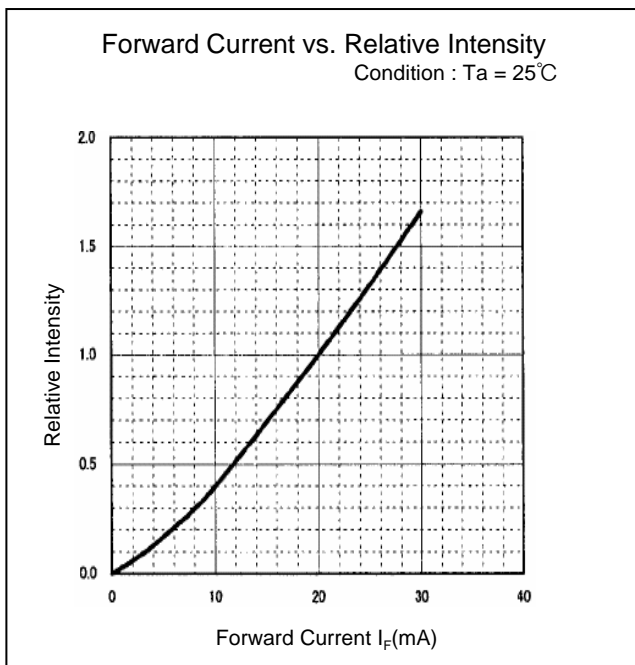
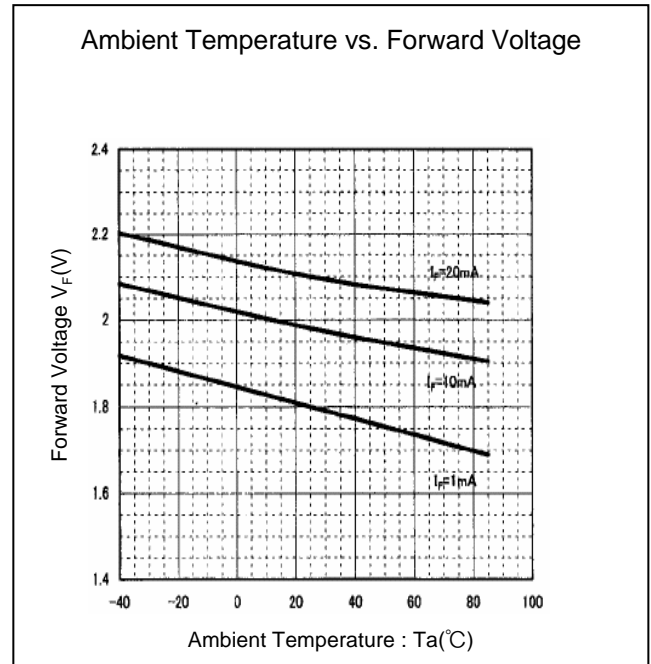
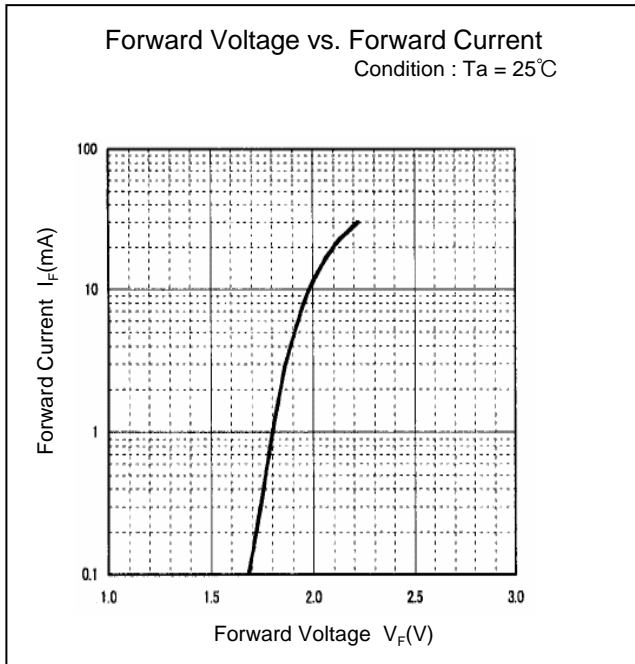
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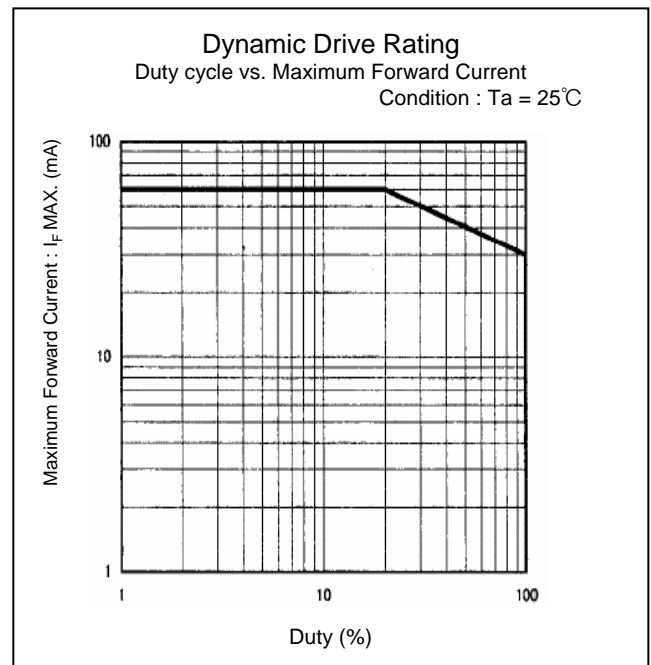
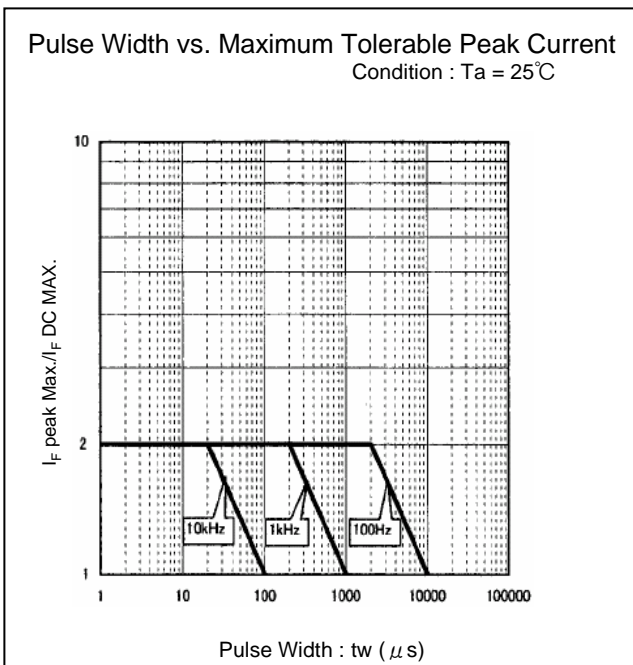
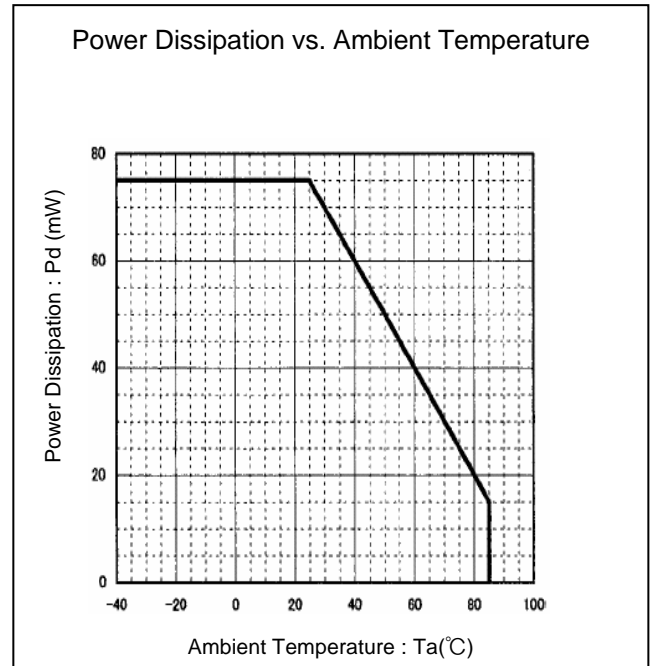
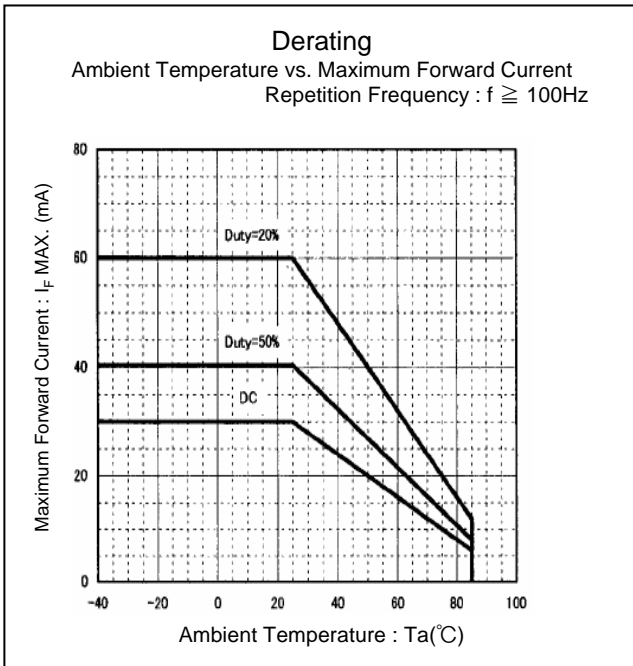
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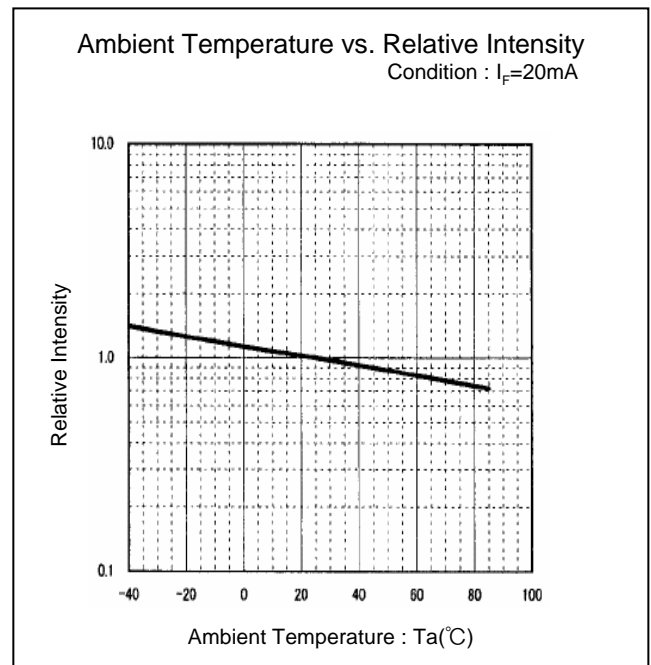
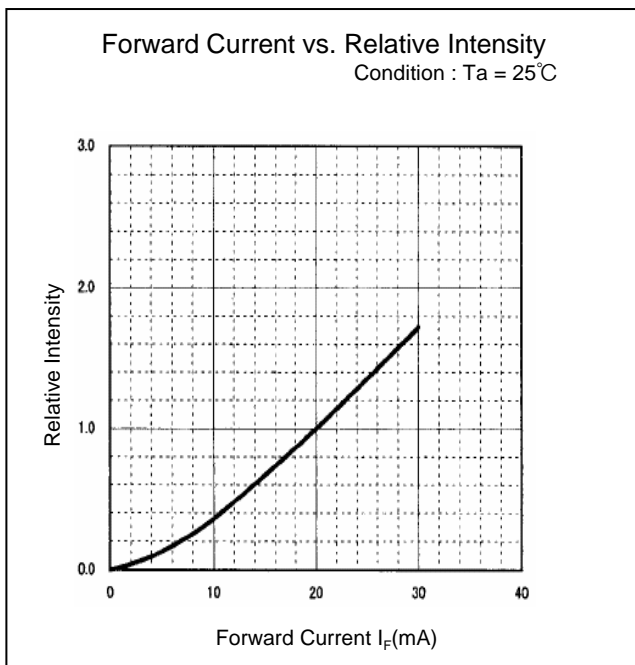
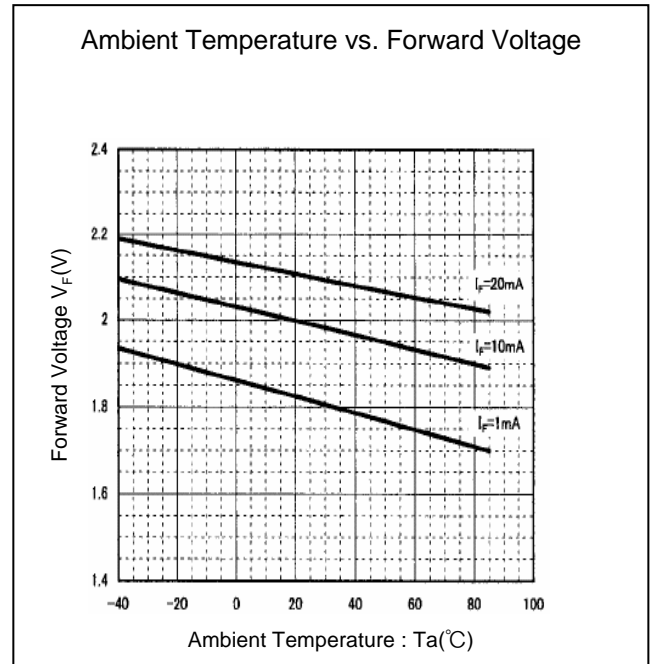
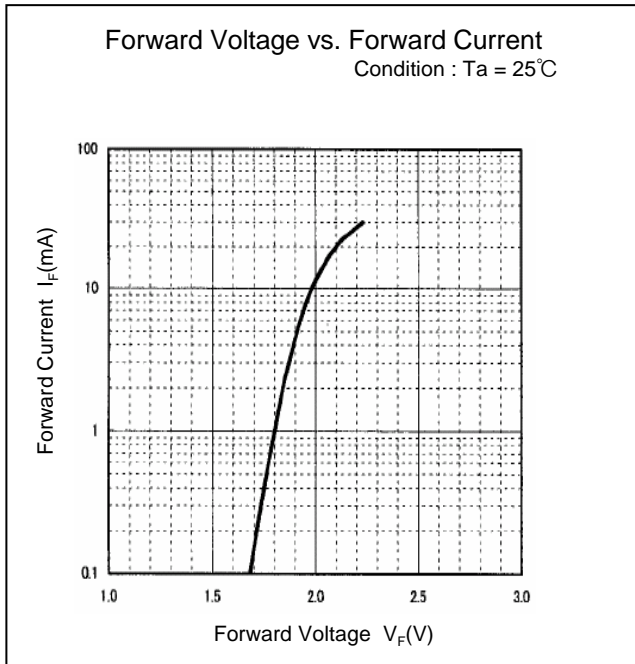
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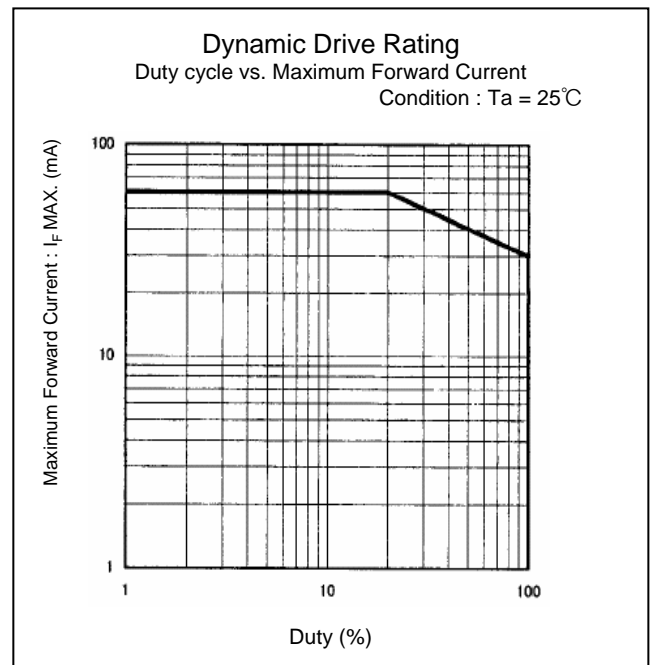
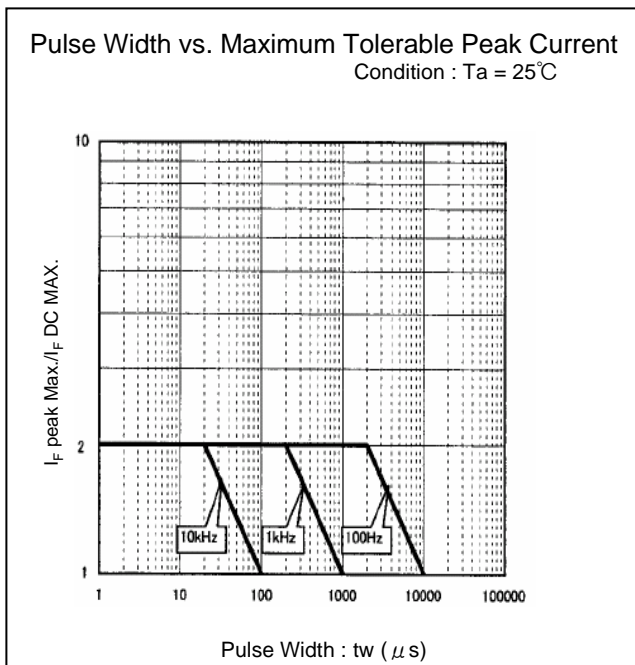
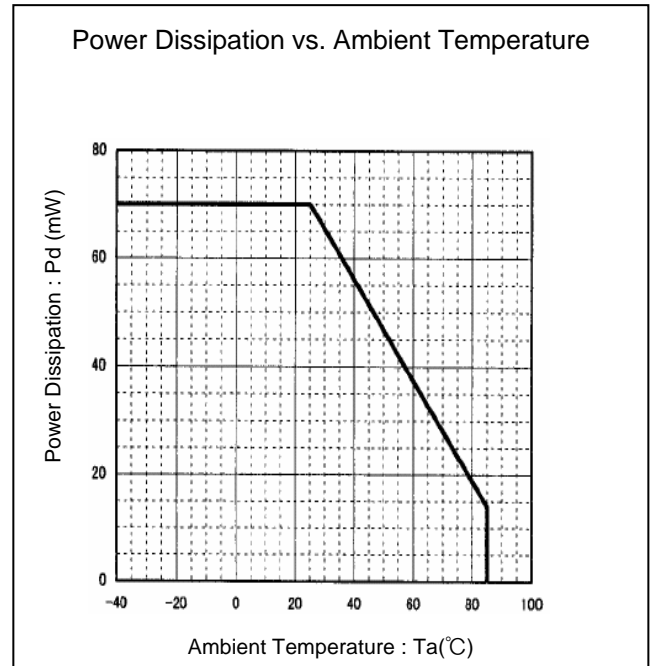
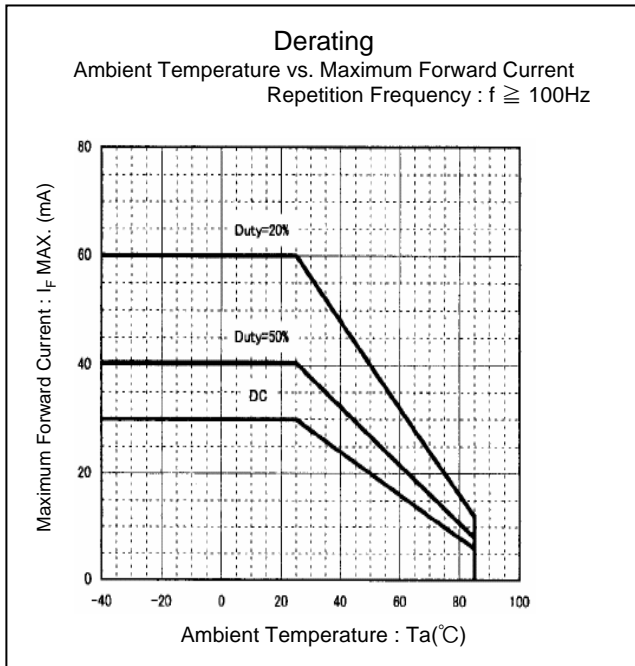
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## Technical Data(4201/4205)

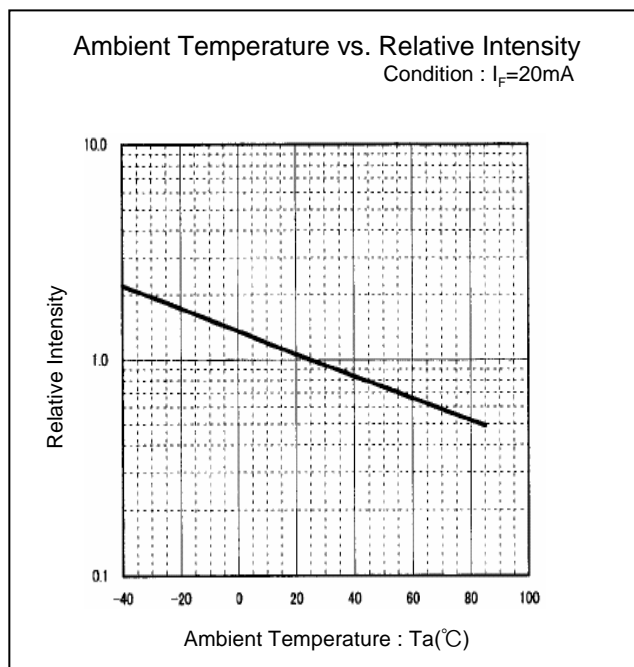
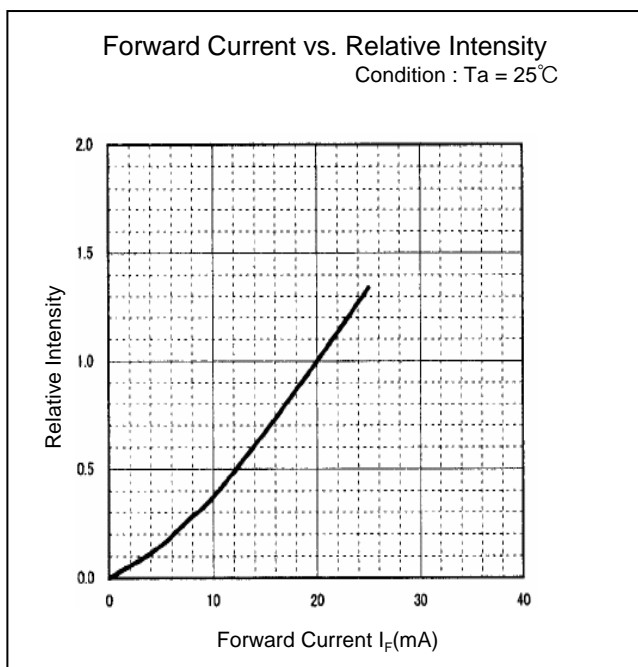
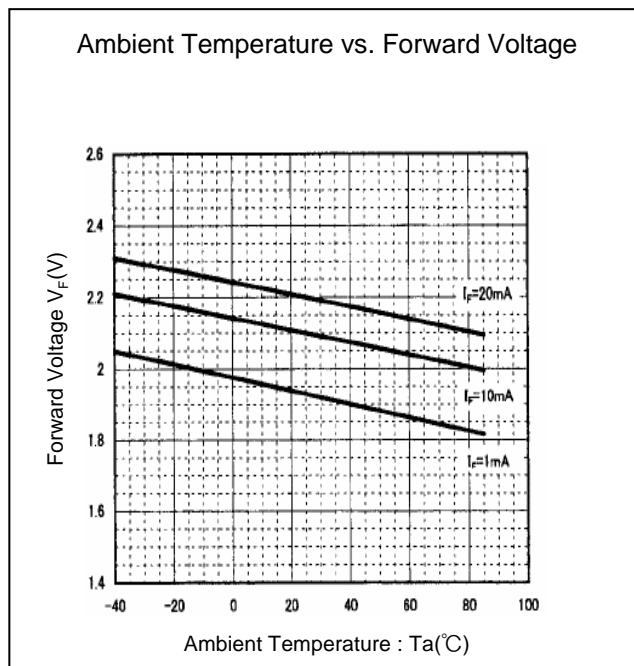
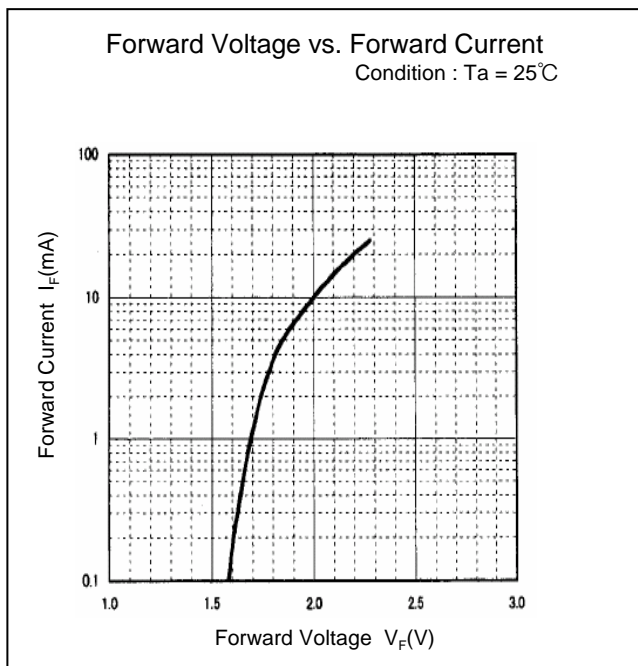


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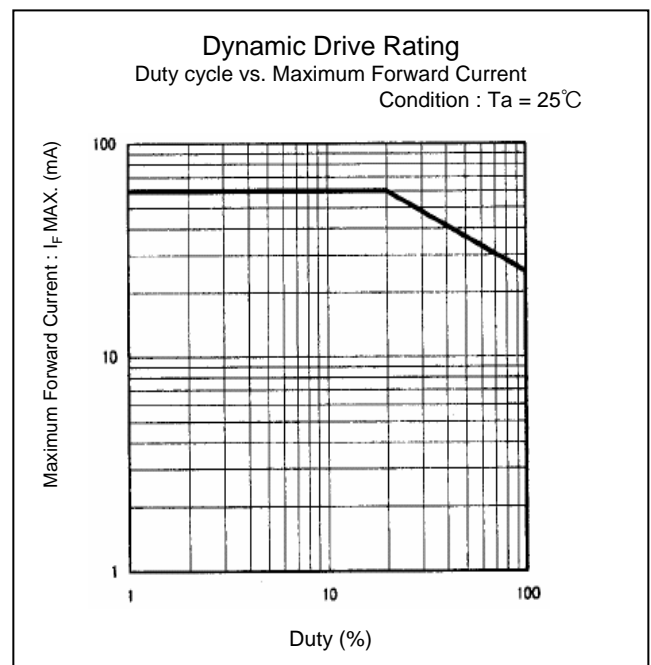
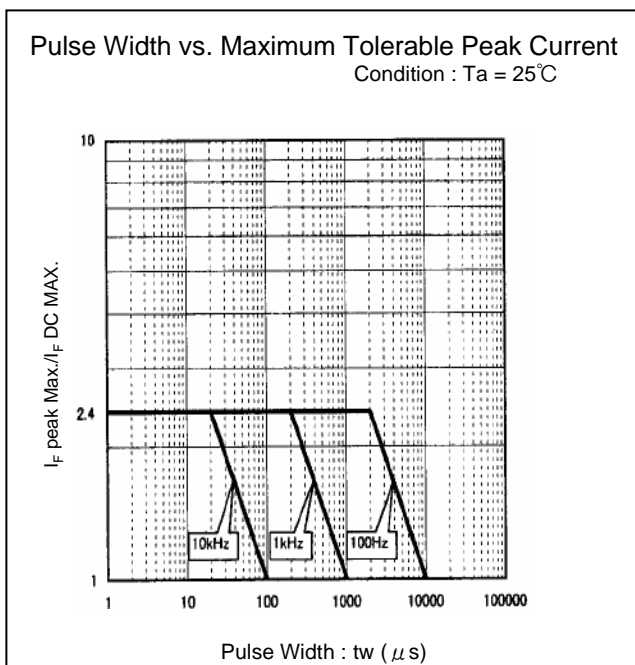
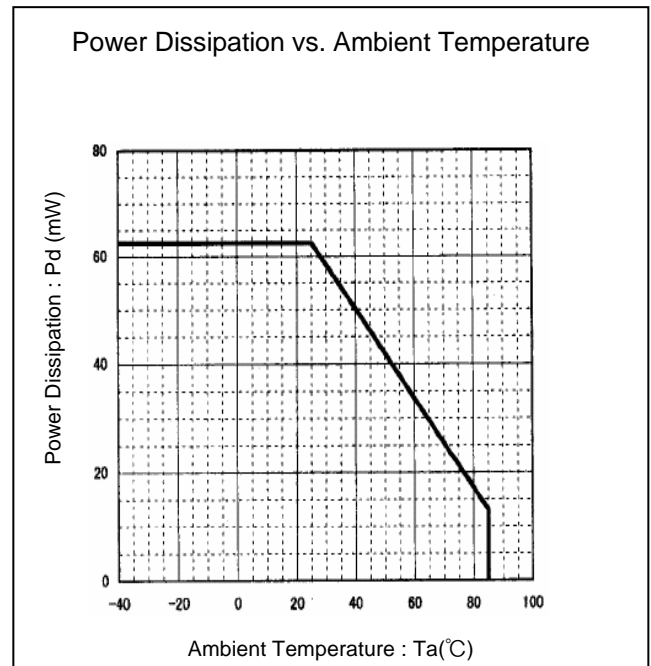
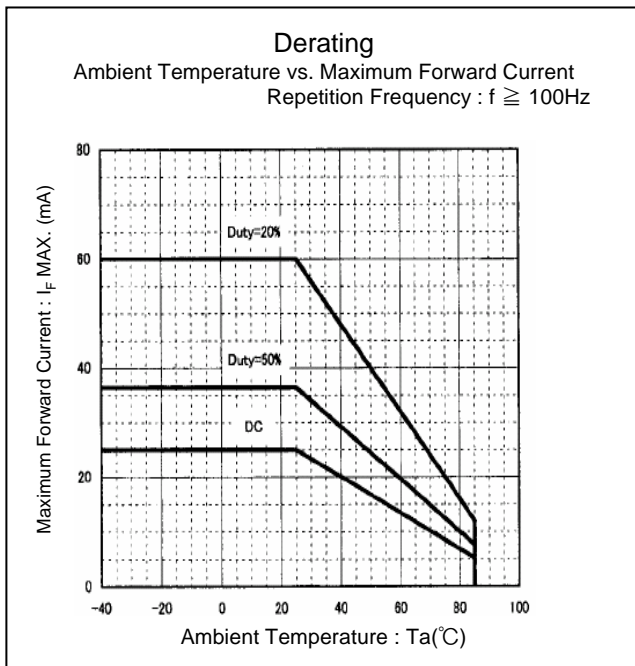




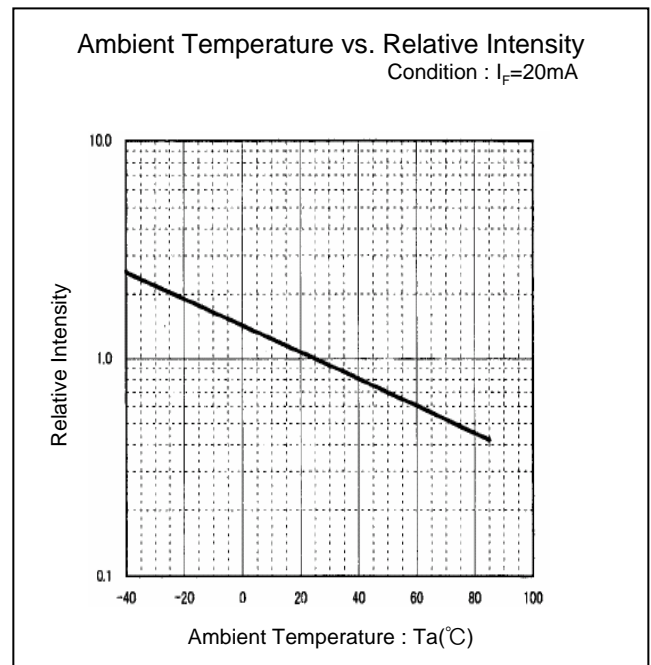
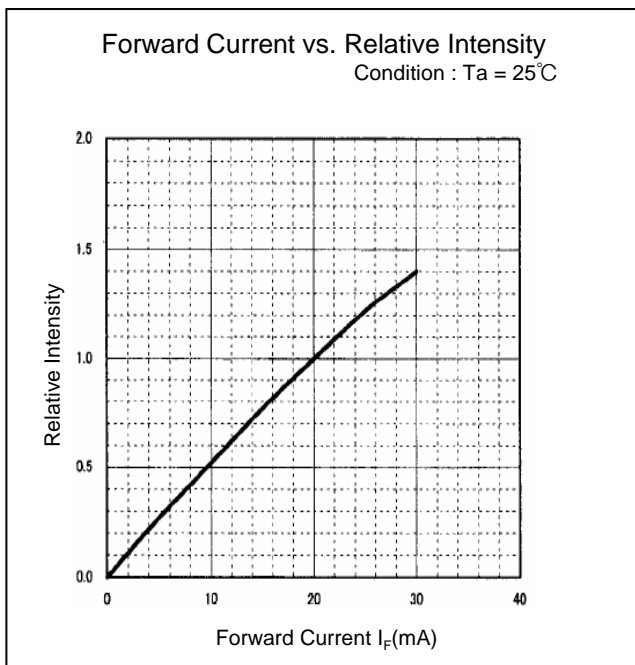
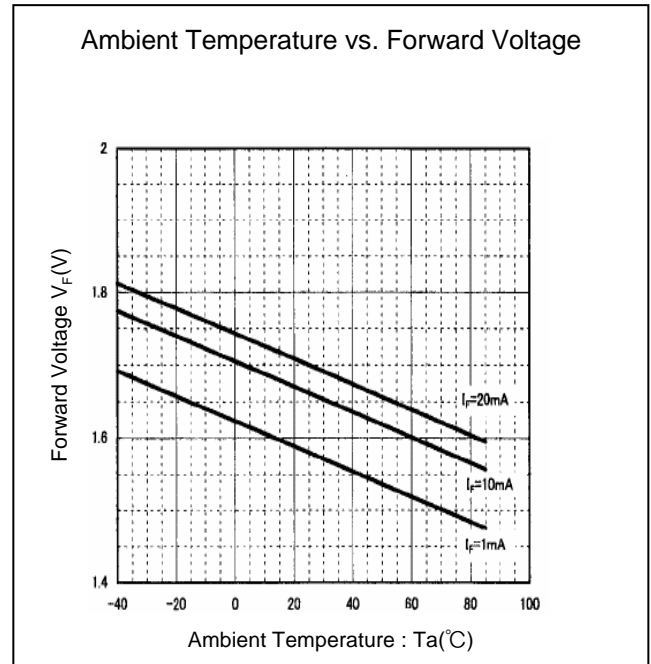
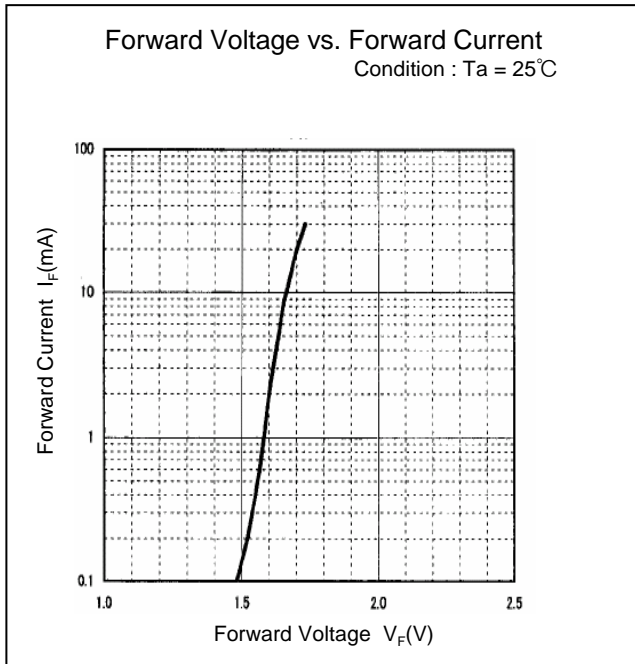
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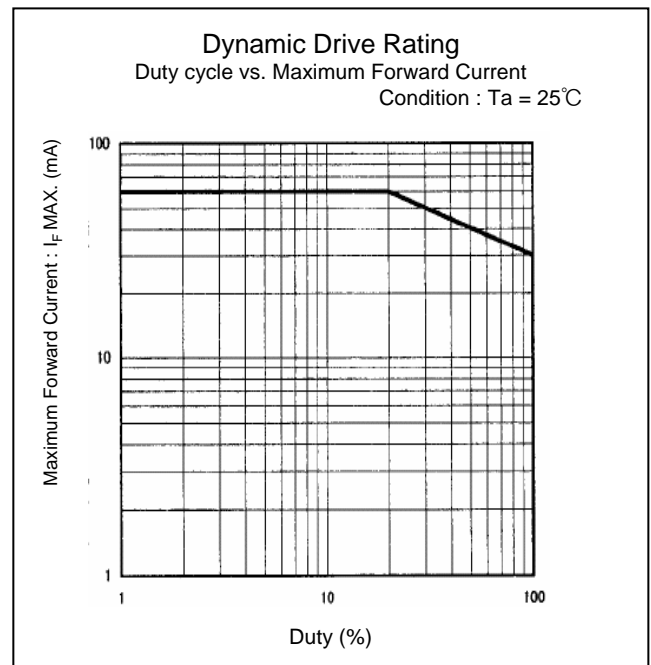
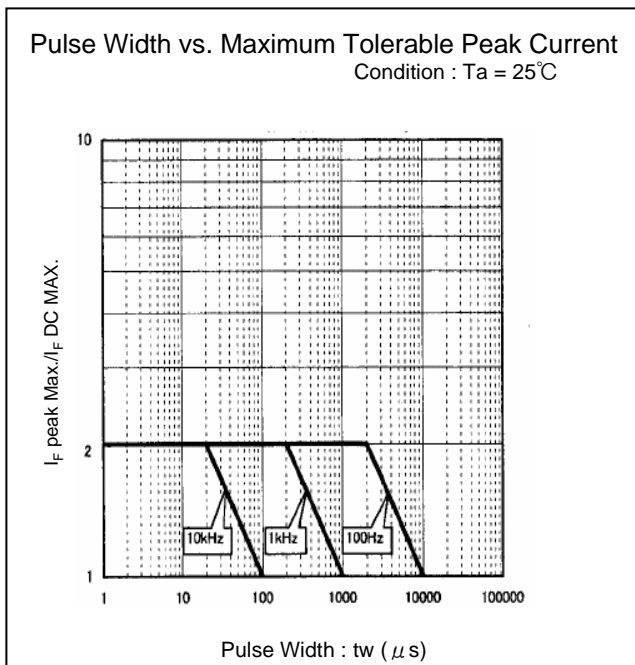
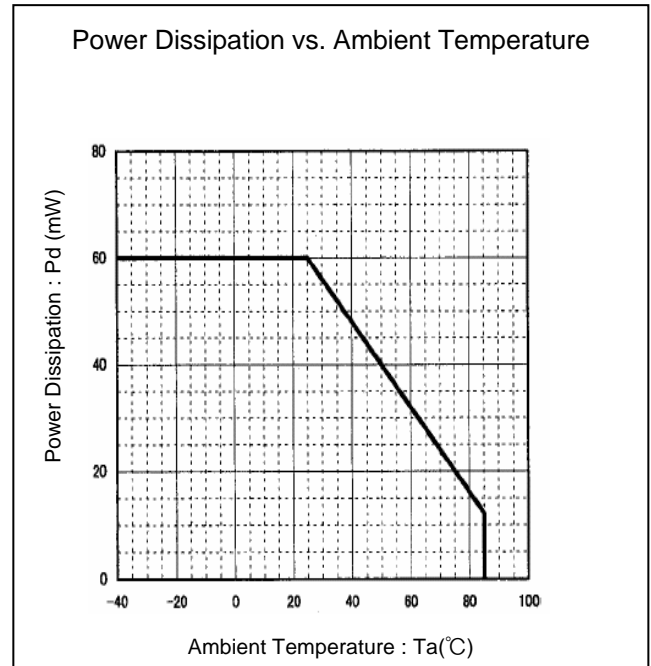
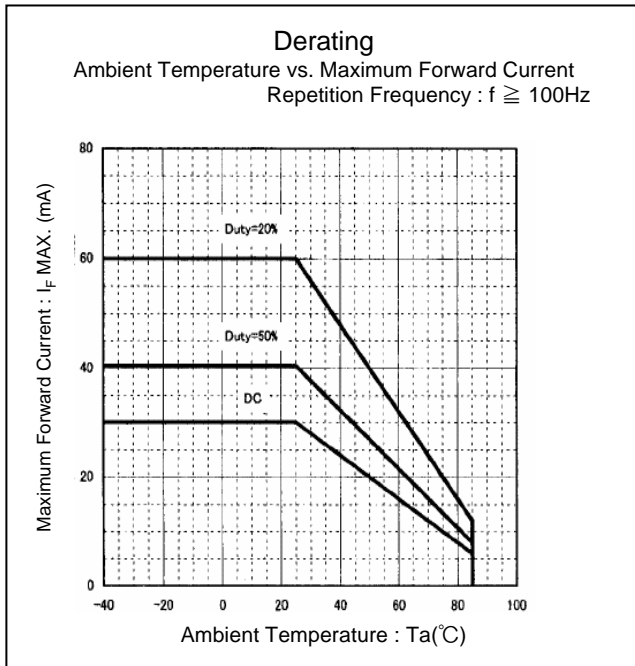
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## Technical Data(2201/2205)



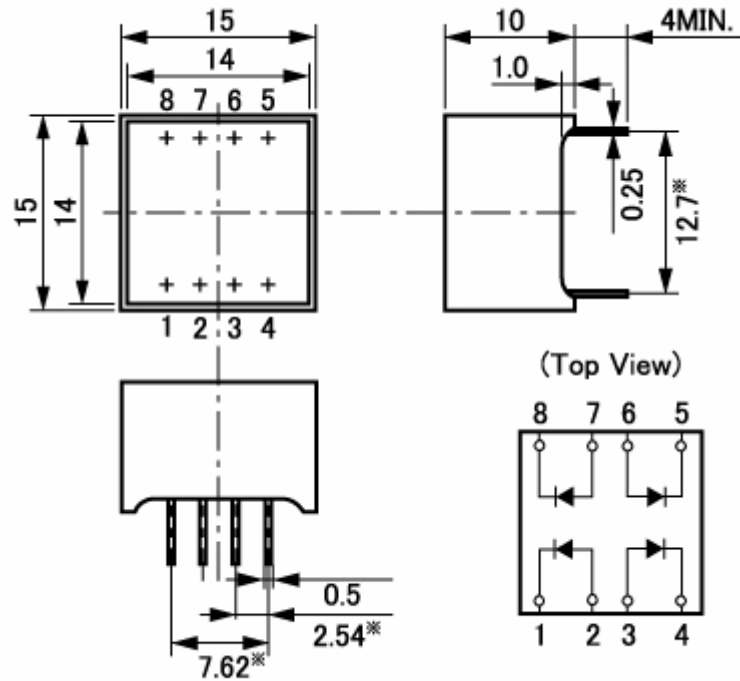
## Technical Data(2201/2205)



## Package Dimensions

(Unit: mm)

(Tolerance :  $\pm 0.25$  mm)



● ※ mark : The measure of lead root

## TTW (Through The Wave) soldering Conditions

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Pre-heating	100 °C 60 s	(MAX.) Resin surface temperature (MAX.)
Solder Bath Temp.	265 °C	(MAX.)
Dipping Time	5 s	(MAX.)
Position	At least 2.0 mm away from the root of lead	

- 1) The dip soldering process shall be 2 times maximum.
- 2) The product shall be cooled to normal temperature before the second dipping process.

## Manual Soldering Conditions

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Iron tip temp.	400 °C	(MAX.) (30 W Max.)
Soldering time and frequency	3 s 2 times	(MAX.) (MAX.)
Position	At least 2.0 mm away from the root of lead	

## Reliability Testing Result

Reliability Testing Result	Applicable Standard	Testing Conditions	Duration	Failure
Room Temp. Operating Life	EAJED-4701/100(101)	Ta = 25°C, If = Maximum Rated Current	1,000 h	0/10
Resistance to Soldering Heat	EAJED-4701/300(302)	260±5°C, 3mm from package base	10s	0/10
Temperature Cycling	EAJED-4701/100(105)	Minimum Rated Storage Temperature(30min) ~Normal Temperature(15min) ~Maximum Rated Storage Temperature(30min) ~Normal Temperature(15min)	5 cycles	0/10
Wet High Temp. Storage Life	EAJED-4701/100(103)	Ta = 60±2°C, RH = 90±5%	1,000 h	0/10
High Temp. Storage Life	EAJED-4701/200(201)	Ta = Maximum Rated Storage Temperature	1,000 h	0/10
Low Temp. Storage Life	EAJED-4701/200(202)	Ta = Minimum Rated Storage Temperature	1,000 h	0/10
Lead Tension	EAJED-4701/400(401)	5N, 1time	10s	0/10
Vibration, Variable Frequency	EAJED-4701/400(403)	98.1m/s <sup>2</sup> (10G), 100 ~ 2KHz sweep for 20min., XYZ each direction	2 h	0/10
Lead Bend	EAJED-4701/400(401)	2.5N, 0°←→ 90°	Twice	0/10
Shock	JSC 7201 A-8	It falls on wood engraving from height of 75cm.	3 times	0/10

## Failure Criteria

Items	Symbols	Conditions	Failure criteria
Luminous Intensity	Iv	If=20mA	Testing Min. Value < Spec. Min. Value x 0.5
Forward Voltage	V <sub>F</sub>	If=20mA	Testing Max. Value ≥ Spec. Max. Value x 1.2
Reverse Current	I <sub>R</sub>	V <sub>R</sub> =4V	Testing Max. Value ≥ Spec. Max. Value x 2.5
Cosmetic Appearance	-	-	Occurrence of notable decoloration, deformation and cracking

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